

MECHANICAL CASE OUTLINE

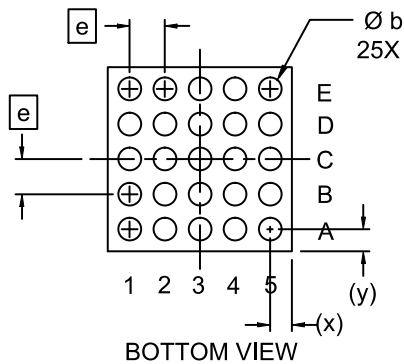
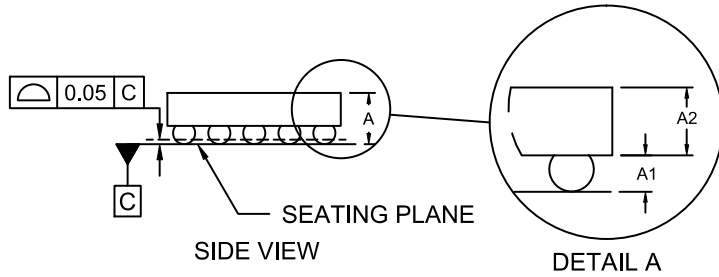
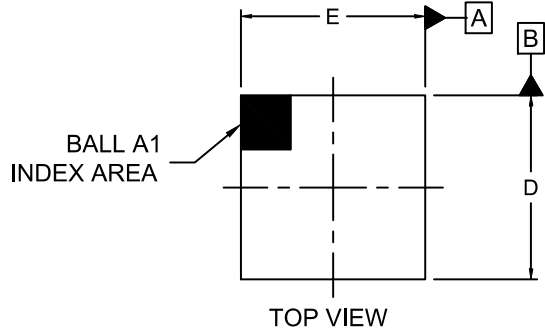
PACKAGE DIMENSIONS

ON Semiconductor®



WLCSP25 2.24x2.28x0.586
CASE 567UZ
ISSUE B

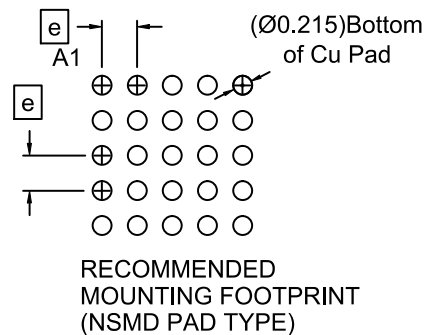
DATE 03 JAN 2018



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.547	0.586	0.625
A1	0.178	0.208	0.238
A2	0.360	0.378	0.396
b	0.24	0.26	0.28
D	2.250	2.280	2.310
E	2.210	2.240	2.270
e	0.40 BSC		
x	0.305	0.320	0.335
y	0.325	0.340	0.355



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